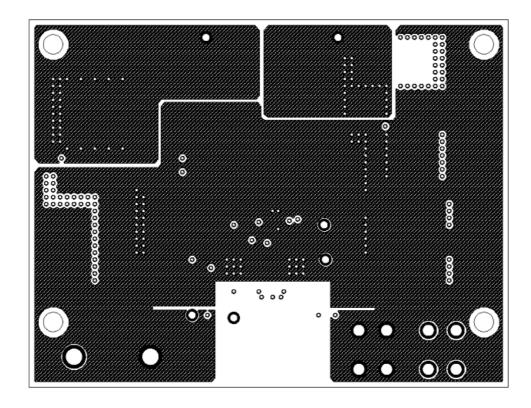
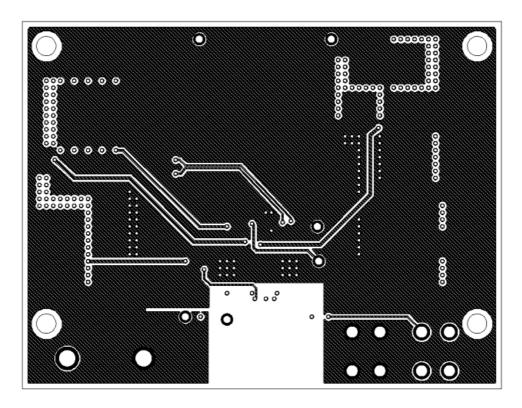


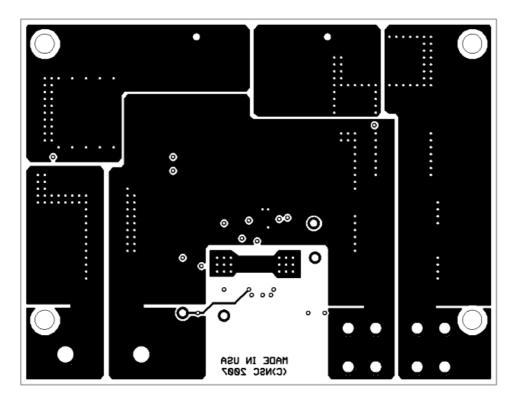
Layer 2



Layer 3



Bottom



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